

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT																		
NATURE OF CONVEYANCE:	ASSIGNMENT																		
CONVEYING PARTY DATA																			
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Misato SAKAMOTO</td> <td>01/30/2012</td> </tr> <tr> <td>Yoshitake KATOU</td> <td>02/07/2012</td> </tr> <tr> <td>Youichi YAMAMOTO</td> <td>01/31/2012</td> </tr> <tr> <td>Takashi KYOUNO</td> <td>01/31/2012</td> </tr> <tr> <td>Chikara YAMAMOTO</td> <td>01/31/2012</td> </tr> <tr> <td>Terukazu MOTOSAWA</td> <td>01/30/2012</td> </tr> <tr> <td>Mitsuo MAEDA</td> <td>01/30/2012</td> </tr> <tr> <td>Hiroshi ITOU</td> <td>01/30/2012</td> </tr> </tbody> </table>		Name	Execution Date	Misato SAKAMOTO	01/30/2012	Yoshitake KATOU	02/07/2012	Youichi YAMAMOTO	01/31/2012	Takashi KYOUNO	01/31/2012	Chikara YAMAMOTO	01/31/2012	Terukazu MOTOSAWA	01/30/2012	Mitsuo MAEDA	01/30/2012	Hiroshi ITOU	01/30/2012
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<table border="1"> <tr> <td>Name:</td> <td>Renesas Electronics Corporation</td> </tr> <tr> <td>Street Address:</td> <td>1753, Shimonumabe, Nakahara-ku,</td> </tr> <tr> <td>City:</td> <td>Kawasaki-shi, Kanagawa</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> </table>		Name:	Renesas Electronics Corporation	Street Address:	1753, Shimonumabe, Nakahara-ku,	City:	Kawasaki-shi, Kanagawa	State/Country:	JAPAN										
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CORRESPONDENCE DATA																			
Fax Number:	(703)610-8686																		
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>																			
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ATTORNEY DOCKET NUMBER:	XA-12089/T3844-18808US01																		
NAME OF SUBMITTER:	Dawn Minter																		
Total Attachments: 1 source=Assignment#page1.tif																			

CH \$40.00 13414062

ASSIGNMENT
(讓 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Electronics Corporation, a corporation organized under the laws of Japan, located at 1753, Shimonumabe, Nakahara-ku, Kawasaki-shi, Kanagawa, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Electronics Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE MANUFACTURING METHOD

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Renesas Electronics Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Electronics Corporation,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Misato Sakamoto</u> Misato SAKAMOTO	<u>January 30, 2012</u>
2) <u>Yoshitake Katou</u> Yoshitake KATOU	<u>Feb 7, 2012</u>
3) <u>Yousichi Yamamoto</u> Yousichi YAMAMOTO	<u>Jan 31, 2012</u>
4) <u>Takashi Kyouno</u> Takashi KYOUNO	<u>Jan 31, 2012</u>
5) <u>Chikara Yamamoto</u> Chikara YAMAMOTO	<u>Jan 31, 2012</u>
6) <u>Terukazu Motosawa</u> Terukazu MOTOSAWA	<u>Jan 30, 2012</u>
7) <u>Mitsuo Maeda</u> Mitsuo MAEDA	<u>Jan 30, 2012</u>
8) <u>Hiroshi Itou</u> Hiroshi ITOU	<u>January 30, 2012</u>
9) _____	_____
10) _____	_____